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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

#### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	34
Number of Gates	30000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3p030-2qng48

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



The CCC block has these key features:

- Wide input frequency range (f<sub>IN CCC</sub>) = 1.5 MHz to 350 MHz
- Output frequency range (f<sub>OUT CCC</sub>) = 0.75 MHz to 350 MHz
- Clock delay adjustment via programmable and fixed delays from -7.56 ns to +11.12 ns
- 2 programmable delay types for clock skew minimization
- Clock frequency synthesis (for PLL only)

Additional CCC specifications:

- Internal phase shift = 0°, 90°, 180°, and 270°. Output phase shift depends on the output divider configuration (for PLL only).
- Output duty cycle = 50% ± 1.5% or better (for PLL only)
- Low output jitter: worst case < 2.5% × clock period peak-to-peak period jitter when single global network used (for PLL only)
- Maximum acquisition time = 300 µs (for PLL only)
- Low power consumption of 5 mW
- Exceptional tolerance to input period jitter— allowable input jitter is up to 1.5 ns (for PLL only)
- Four precise phases; maximum misalignment between adjacent phases of 40 ps × (350 MHz / f<sub>OUT\_CCC</sub>) (for PLL only)

# **Global Clocking**

ProASIC3 devices have extensive support for multiple clocking domains. In addition to the CCC and PLL support described above, there is a comprehensive global clock distribution network.

Each VersaTile input and output port has access to nine VersaNets: six chip (main) and three quadrant global networks. The VersaNets can be driven by the CCC or directly accessed from the core via multiplexers (MUXes). The VersaNets can be used to distribute low-skew clock signals or for rapid distribution of high fanout nets.



# I/Os with Advanced I/O Standards

The ProASIC3 family of FPGAs features a flexible I/O structure, supporting a range of voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V). ProASIC3 FPGAs support many different I/O standards—single-ended and differential.

The I/Os are organized into banks, with two or four banks per device. The configuration of these banks determines the I/O standards supported (Table 1-1).

		I/O Standards Supported						
I/O Bank Type	Device and Bank Location	LVTTL/ LVCMOS	PCI/PCI-X	LVPECL, LVDS, B-LVDS, M-LVDS				
Advanced	East and west Banks of A3P250 and larger devices	$\checkmark$	$\checkmark$	$\checkmark$				
Standard Plus	North and south banks of A3P250 and larger devices All banks of A3P060 and A3P125	$\checkmark$	$\checkmark$	Not supported				
Standard	All banks of A3P015 and A3P030	$\checkmark$	Not supported	Not supported				

Each I/O module contains several input, output, and enable registers. These registers allow the implementation of the following:

- Single-Data-Rate applications
- Double-Data-Rate applications—DDR LVDS, B-LVDS, and M-LVDS I/Os for point-to-point communications

ProASIC3 banks for the A3P250 device and above support LVPECL, LVDS, B-LVDS and M-LVDS. B-LVDS and M-LVDS can support up to 20 loads.

Hot-swap (also called hot-plug, or hot-insertion) is the operation of hot-insertion or hot-removal of a card in a poweredup system.

Cold-sparing (also called cold-swap) refers to the ability of a device to leave system data undisturbed when the system is powered up, while the component itself is powered down, or when power supplies are floating.

# Wide Range I/O Support

ProASIC3 devices support JEDEC-defined wide range I/O operation. ProASIC3 supports the JESD8-B specification, covering both 3 V and 3.3 V supplies, for an effective operating range of 2.7 V to 3.6 V.

Wider I/O range means designers can eliminate power supplies or power conditioning components from the board or move to less costly components with greater tolerances. Wide range eases I/O bank management and provides enhanced protection from system voltage spikes, while providing the flexibility to easily run custom voltage applications.

# **Specifying I/O States During Programming**

You can modify the I/O states during programming in FlashPro. In FlashPro, this feature is supported for PDB files generated from Designer v8.5 or greater. See the *FlashPro User's Guide* for more information.

- Note: PDB files generated from Designer v8.1 to Designer v8.4 (including all service packs) have limited display of Pin Numbers only.
  - 1. Load a PDB from the FlashPro GUI. You must have a PDB loaded to modify the I/O states during programming.
  - 2. From the FlashPro GUI, click PDB Configuration. A FlashPoint Programming File Generator window appears.
  - 3. Click the Specify I/O States During Programming button to display the Specify I/O States During Programming dialog box.
  - 4. Sort the pins as desired by clicking any of the column headers to sort the entries by that header. Select the I/Os you wish to modify (Figure 1-4 on page 1-8).
  - 5. Set the I/O Output State. You can set Basic I/O settings if you want to use the default I/O settings for your pins, or use Custom I/O settings to customize the settings for each pin. Basic I/O state settings:
    - 1 I/O is set to drive out logic High

# Table 2-19 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings

		Equiv.			VIL	VIH		VOL	VOH		
I/O Standard	Drive Strength	Software Default Drive Strength Option <sup>2</sup>	Slew Rate	Min V	Max V	Min V	Max V	Max V	Min V	IOL <sup>1</sup> mA	IOH <sup>1</sup> mA
3.3 V LVTTL / 3.3 V LVCMOS	12 mA	12 mA	High	-0.3	0.8	2	3.6	0.4	2.4	12	12
3.3 V LVCMOS Wide Range <sup>3</sup>	100 µA	12 mA	High	-0.3	0.8	2	3.6	0.2	VCCI – 0.2	0.1	0.1
2.5 V LVCMOS	12 mA	12 mA	High	-0.3	0.7	1.7	2.7	0.7	1.7	12	12
1.8 V LVCMOS	8 mA	8 mA	High	-0.3	0.35 * VCCI	0.65 * VCCI	1.9	0.45	VCCI – 0.45	8	8
1.5 V LVCMOS	4 mA	4 mA	High	-0.3	0.35 * VCCI	0.65 * VCCI	1.6	0.25 * VCCI	0.75 * VCCI	4	4
3.3 V PCI		-		-	Per P	CI specification	ons				
3.3 V PCI-X					Per PC	I-X specificat	ions				

Applicable to Standard Plus I/O Banks

Notes:

1. Currents are measured at 85°C junction temperature.

2. 3.3 V LVCMOS wide range is applicable to 100 µA drive strength only. The configuration will NOT operate at the equivalent software default drive strength. These values are for Normal Ranges ONLY.

3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD8-B specification.



# Table 2-24 • Summary of I/O Timing Characteristics—Software Default Settings

#### -2 Speed Grade, Commercial-Case Conditions: T<sub>J</sub> = 70°C, Worst Case VCC = 1.425 V, Worst-Case VCCI (per standard) 1

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٨	١dv	a	nc	ec	ł	I/O	Ban	ks	;		

I/O Standard	Drive Strength	Equiv. Software Default Drive Strength Option <sup>1</sup>	Slew Rate	Capacitive Load (pF)	External Resistor ( $\Omega$ )	t <sub>bour</sub> (ns)	t <sub>DP</sub> (ns)	t <sub>DIN</sub> (ns)	t <sub>PY</sub> (ns)	t <sub>Eout</sub> (ns)	t <sub>ZL</sub> (ns)	t <sub>ZH</sub> (ns)	t <sub>LZ</sub> (ns)	t <sub>HZ</sub> (ns)	t <sub>ZLS</sub> (ns)	t <sub>ZHS</sub> (ns)	Units
3.3 V LVTTL / 3.3 V LVCMOS	12 mA	12 mA	High	35	-	0.45	2.64	0.03	0.76	0.32	2.69	2.11	2.40	2.68	4.36	3.78	ns
3.3 V LVCMOS Wide Range <sup>2</sup>	100 µA	12 mA	High	35	-	0.45	4.08	0.03	0.76	0.32	4.08	3.20	3.71	4.14	6.61	5.74	ns
2.5 V LVCMOS	12 mA	12 mA	High	35	-	0.45	2.66	0.03	0.98	0.32	2.71	2.56	2.47	2.57	4.38	4.23	ns
1.8 V LVCMOS	12 mA	12 mA	High	35	-	0.45	2.64	0.03	0.91	0.32	2.69	2.27	2.76	3.05	4.36	3.94	ns
1.5 V LVCMOS	12 mA	12 mA	High	35	-	0.45	3.05	0.03	1.07	0.32	3.10	2.67	2.95	3.14	4.77	4.34	ns
3.3 V PCI	Per PCI spec	-	High	10	25 <sup>4</sup>	0.45	2.00	0.03	0.65	0.32	2.04	1.46	2.40	2.68	3.71	3.13	ns
3.3 V PCI-X	Per PCI-X spec	-	High	10	25 <sup>4</sup>	0.45	2.00	0.03	0.62	0.32	2.04	1.46	2.40	2.68	3.71	3.13	ns
LVDS	24 mA	_	High	-	-	0.45	1.37	0.03	1.20	_	_	_	_	-	_	-	ns
LVPECL	24 mA	-	High	-	-	0.45	1.34	0.03	1.05	_	_	_	_	_	_	-	ns

Notes:

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.

2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.

3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

4. Resistance is used to measure I/O propagation delays as defined in PCI specifications. See Figure 2-11 on page 2-64 for connectivity. This resistor is not required during normal operation.



## Table 2-33 • I/O Short Currents IOSH/IOSL Applicable to Standard Plus I/O Banks

	Drive Strength	IOSL (mA) <sup>1</sup>	IOSH (mA) <sup>1</sup>
3.3 V LVTTL / 3.3 V LVCMOS	2 mA	27	25
	4 mA	27	25
	6 mA	54	51
	8 mA	54	51
	12 mA	109	103
	16 mA	109	103
3.3 V LVCMOS Wide Range <sup>2</sup>	100 µA	Same as regular 3.3 V LVCMOS	Same as regular 3.3 V LVCMOS
2.5 V LVCMOS	2 mA	18	16
	4 mA	18	16
	6 mA	37	32
	8 mA	37	32
	12 mA	74	65
1.8 V LVCMOS	2 mA	11	9
	4 mA	22	17
	6 mA	44	35
	8 mA	44	35
1.5 V LVCMOS	2 mA	16	13
	4 mA	33	25
3.3 V PCI/PCI-X	Per PCI/PCI-X specification	109	103

Notes:

1.  $T_J = 100^{\circ}C$ 

 Applicable to 3.3 V LVCMOS Wide Range. IOSL/IOSH dependent on the I/O buffer drive strength selected for wide range applications. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD8-B specification.

and Switchi <b>Table 2-62 •</b>	2.5 V LV	cteristics CMOS H	igh Sle	W	T - 70	N°C Wor	et Cae		- 1 425	V Wor		Power	Matters.
	Applicat	ole to Sta	indard	Plus I/C	D Bank	s , wor	51-0456	, vcc -	- 1.423	v, wor	51-0450		2.3 V
Drive Strength	Speed Grade	t <sub>DOUT</sub>	t <sub>DP</sub>	t <sub>DIN</sub>	t <sub>PY</sub>	t <sub>EOUT</sub>	t <sub>ZL</sub>	t <sub>zH</sub>	t <sub>LZ</sub>	t <sub>HZ</sub>	t <sub>zLS</sub>	t <sub>zHS</sub>	Units
4 mA	Std.	0.66	8.28	0.04	1.30	0.43	7.41	8.28	2.25	2.07	9.64	10.51	ns
	-1	0.56	7.04	0.04	1.10	0.36	6.30	7.04	1.92	1.76	8.20	8.94	ns
	-2	0.49	6.18	0.03	0.97	0.32	5.53	6.18	1.68	1.55	7.20	7.85	ns
6 mA	Std.	0.66	4.85	0.04	1.30	0.43	4.65	4.85	2.59	2.71	6.88	7.09	ns
	-1	0.56	4.13	0.04	1.10	0.36	3.95	4.13	2.20	2.31	5.85	6.03	ns
	-2	0.49	3.62	0.03	0.97	0.32	3.47	3.62	1.93	2.02	5.14	5.29	ns
8 mA	Std.	0.66	4.85	0.04	1.30	0.43	4.65	4.85	2.59	2.71	6.88	7.09	ns
	-1	0.56	4.13	0.04	1.10	0.36	3.95	4.13	2.20	2.31	5.85	6.03	ns
	-2	0.49	3.62	0.03	0.97	0.32	3.47	3.62	1.93	2.02	5.14	5.29	ns
12 mA	Std.	0.66	3.21	0.04	1.30	0.43	3.27	3.14	2.82	3.11	5.50	5.38	ns
	-1	0.56	2.73	0.04	1.10	0.36	2.78	2.67	2.40	2.65	4.68	4.57	ns
	-2	0.49	2.39	0.03	0.97	0.32	2.44	2.35	2.11	2.32	4.11	4.02	ns

Microsomi

Notes:

1. Software default selection highlighted in gray.

2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

# Table 2-63 • 2.5 V LVCMOS Low Slew Commercial-Case Conditions: T<sub>J</sub> = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t <sub>DOUT</sub>	t <sub>DP</sub>	t <sub>DIN</sub>	t <sub>PY</sub>	t <sub>EOUT</sub>	t <sub>ZL</sub>	t <sub>zH</sub>	t <sub>LZ</sub>	t <sub>HZ</sub>	t <sub>zLS</sub>	t <sub>zHS</sub>	Units
4 mA	Std.	0.66	10.84	0.04	1.30	0.43	10.64	10.84	2.26	1.99	12.87	13.08	ns
	–1	0.56	9.22	0.04	1.10	0.36	9.05	9.22	1.92	1.69	10.95	11.12	ns
	-2	0.49	8.10	0.03	0.97	0.32	7.94	8.10	1.68	1.49	9.61	9.77	ns
6 mA	Std.	0.66	7.37	0.04	1.30	0.43	7.50	7.36	2.59	2.61	9.74	9.60	ns
	-1	0.56	6.27	0.04	1.10	0.36	6.38	6.26	2.20	2.22	8.29	8.16	ns
	-2	0.49	5.50	0.03	0.97	0.32	5.60	5.50	1.93	1.95	7.27	7.17	ns
8 mA	Std.	0.66	7.37	0.04	1.30	0.43	7.50	7.36	2.59	2.61	9.74	9.60	ns
	-1	0.56	6.27	0.04	1.10	0.36	6.38	6.26	2.20	2.22	8.29	8.16	ns
	-2	0.49	5.50	0.03	0.97	0.32	5.60	5.50	1.93	1.95	7.27	7.17	ns
12 mA	Std.	0.66	5.63	0.04	1.30	0.43	5.73	5.51	2.83	3.01	7.97	7.74	ns
	-1	0.56	4.79	0.04	1.10	0.36	4.88	4.68	2.41	2.56	6.78	6.59	ns
	-2	0.49	4.20	0.03	0.97	0.32	4.28	4.11	2.11	2.25	5.95	5.78	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.



## Table 2-73 • 1.8 V LVCMOS Low Slew

Commercial-Case Conditions: T <sub>J</sub> = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V
Applicable to Standard Plus I/O Banks

Drive Strength	Speed Grade	t <sub>DOUT</sub>	t <sub>DP</sub>	t <sub>DIN</sub>	t <sub>PY</sub>	t <sub>EOUT</sub>	t <sub>ZL</sub>	t <sub>zH</sub>	t <sub>LZ</sub>	t <sub>HZ</sub>	t <sub>ZLS</sub>	t <sub>zHS</sub>	Units
2 mA	Std.	0.66	14.80	0.04	1.20	0.43	13.49	14.80	2.25	1.46	15.73	17.04	ns
	-1	0.56	12.59	0.04	1.02	0.36	11.48	12.59	1.91	1.25	13.38	14.49	ns
	-2	0.49	11.05	0.03	0.90	0.32	10.08	11.05	1.68	1.09	11.75	12.72	ns
4 mA	Std.	0.66	9.90	0.04	1.20	0.43	9.73	9.90	2.65	2.50	11.97	12.13	ns
	-1	0.56	8.42	0.04	1.02	0.36	8.28	8.42	2.26	2.12	10.18	10.32	ns
	-2	0.49	7.39	0.03	0.90	0.32	7.27	7.39	1.98	1.86	8.94	9.06	ns
6 mA	Std.	0.66	7.44	0.04	1.20	0.43	7.58	7.32	2.94	2.99	9.81	9.56	ns
	-1	0.56	6.33	0.04	1.02	0.36	6.44	6.23	2.50	2.54	8.35	8.13	ns
	-2	0.49	5.55	0.03	0.90	0.32	5.66	5.47	2.19	2.23	7.33	7.14	ns
8 mA	Std.	0.66	7.44	0.04	1.20	0.43	7.58	7.32	2.94	2.99	9.81	9.56	ns
	-1	0.56	6.33	0.04	1.02	0.36	6.44	6.23	2.50	2.54	8.35	8.13	ns
	-2	0.49	5.55	0.03	0.90	0.32	5.66	5.47	2.19	2.23	7.33	7.14	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

# Table 2-74 • 1.8 V LVCMOS High SlewCommercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 VApplicable to Standard I/O Banks

Drive Strength	Speed Grade	t <sub>DOUT</sub>	t <sub>DP</sub>	t <sub>DIN</sub>	t <sub>PY</sub>	t <sub>EOUT</sub>	t <sub>ZL</sub>	t <sub>zH</sub>	t <sub>LZ</sub>	t <sub>HZ</sub>	Units
2 mA	Std.	0.66	11.21	0.04	1.20	0.43	8.53	11.21	1.99	1.21	ns
	-1	0.56	9.54	0.04	1.02	0.36	7.26	9.54	1.69	1.03	ns
	-2	0.49	8.37	0.03	0.90	0.32	6.37	8.37	1.49	0.90	ns
4 mA	Std.	0.66	6.34	0.04	1.20	0.43	5.38	6.34	2.41	2.48	ns
	-1	0.56	5.40	0.04	1.02	0.36	4.58	5.40	2.05	2.11	ns
	-2	0.49	4.74	0.03	0.90	0.32	4.02	4.74	1.80	1.85	ns

Notes:

1. Software default selection highlighted in gray.

2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.



### Table 2-75 • 1.8 V LVCMOS Low Slew

Commercial-Case Conditions:  $T_J$  = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V Applicable to Standard I/O Banks

Drive Strength	Speed Grade	t <sub>DOUT</sub>	t <sub>DP</sub>	t <sub>DIN</sub>	t <sub>PY</sub>	t <sub>EOUT</sub>	t <sub>ZL</sub>	t <sub>zH</sub>	t <sub>LZ</sub>	t <sub>HZ</sub>	Units
2 mA	Std.	0.66	15.01	0.04	1.20	0.43	13.15	15.01	1.99	1.99	ns
	-1	0.56	12.77	0.04	1.02	0.36	11.19	12.77	1.70	1.70	ns
	-2	0.49	11.21	0.03	0.90	0.32	9.82	11.21	1.49	1.49	ns
4 mA	Std.	0.66	10.10	0.04	1.20	0.43	9.55	10.10	2.41	2.37	ns
	-1	0.56	8.59	0.04	1.02	0.36	8.13	8.59	2.05	2.02	ns
	-2	0.49	7.54	0.03	0.90	0.32	7.13	7.54	1.80	1.77	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

# 1.5 V LVCMOS (JESD8-11)

Low-Voltage CMOS for 1.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.5 V applications. It uses a 1.5 V input buffer and a push-pull output buffer.

# Table 2-76 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks

1.5 V LVCMOS		VIL	VIH		VOL	VOH	IOL	юн	IOSL	IOSH	IIL¹	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max., V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	μA <sup>4</sup>	μA <sup>4</sup>
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.575	0.25 * VCCI	0.75 * VCCI	2	2	16	13	10	10
4 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.575	0.25 * VCCI	0.75 * VCCI	4	4	33	25	10	10
6 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.575	0.25 * VCCI	0.75 * VCCI	6	6	39	32	10	10
8 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.575	0.25 * VCCI	0.75 * VCCI	8	8	55	66	10	10
12 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.575	0.25 * VCCI	0.75 * VCCI	12	12	55	66	10	10

Notes:

1. IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.

2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges

3. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.

4. Currents are measured at 85°C junction temperature.

5. Software default selection highlighted in gray.



# **VersaTile Characteristics**

# VersaTile Specifications as a Combinatorial Module

The ProASIC3 library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the *Fusion, IGLOO®/e, and ProASIC3/E Macro Library Guide*.



Figure 2-24 • Sample of Combinatorial Cells





Figure 2-25 • Timing Model and Waveforms



# Timing Characteristics

# Table 2-107 • A3P015 Global Resource

# Commercial-Case Conditions: T<sub>J</sub> = 70°C, VCC = 1.425 V

		-	-2		-1	Std.		
Parameter	Description	Min. <sup>1</sup>	Max. <sup>2</sup>	Min. <sup>1</sup>	Max. <sup>2</sup>	Min. <sup>1</sup>	Max. <sup>2</sup>	Units
t <sub>RCKL</sub>	Input Low Delay for Global Clock	0.66	0.81	0.75	0.92	0.88	1.08	ns
t <sub>RCKH</sub>	Input High Delay for Global Clock	0.67	0.84	0.76	0.96	0.89	1.13	ns
t <sub>RCKMPWH</sub>	Minimum Pulse Width High for Global Clock	0.75		0.85		1.00		ns
t <sub>RCKMPWL</sub>	Minimum Pulse Width Low for Global Clock	0.85		0.96		1.13		ns
t <sub>RCKSW</sub>	Maximum Skew for Global Clock		0.18		0.21		0.25	ns

#### Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).

2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).

3. For specific junction temperature and voltage-supply levels, refer to Table 2-6 on page 2-6 for derating values.

## Table 2-108 • A3P030 Global Resource

### Commercial-Case Conditions: T<sub>J</sub> = 70°C, VCC = 1.425 V

		-	-2		-1		Std.	
Parameter	Description	Min. <sup>1</sup>	Max. <sup>2</sup>	Min. <sup>1</sup>	Max. <sup>2</sup>	Min. <sup>1</sup>	Max. <sup>2</sup>	Units
t <sub>RCKL</sub>	Input Low Delay for Global Clock	0.67	0.81	0.76	0.92	0.89	1.09	ns
<sup>t</sup> <sub>RCKH</sub>	Input High Delay for Global Clock	0.68	0.85	0.77	0.97	0.91	1.14	ns
t <sub>RCKMPWH</sub>	Minimum Pulse Width High for Global Clock	0.75		0.85		1.00		ns
t <sub>RCKMPWL</sub>	Minimum Pulse Width Low for Global Clock	0.85		0.96		1.13		ns
t <sub>RCKSW</sub>	Maximum Skew for Global Clock		0.18		0.21		0.24	ns

#### Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).

2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).

3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.



QN68					
Pin Number	A3P030 Function				
1	IO82RSB1				
2	IO80RSB1				
3 IO78RSB1					
4	IO76RSB1				
5	GEC0/IO73RSB1				
6	GEA0/IO72RSB1				
7	GEB0/IO71RSB1				
8	VCC				
9	GND				
10	VCCIB1				
11	IO68RSB1				
12	IO67RSB1				
13	IO66RSB1				
14	IO65RSB1				
15	IO64RSB1				
16	IO63RSB1				
17	IO62RSB1				
18	IO60RSB1				
19	IO58RSB1				
20	IO56RSB1				
21	IO54RSB1				
22	IO52RSB1				
23	IO51RSB1				
24	VCC				
25	GND				
26	VCCIB1				
27	IO50RSB1				
28	IO48RSB1				
29	IO46RSB1				
30	IO44RSB1				
31	IO42RSB1				
32	ТСК				
33	TDI				
34	TMS				
35	VPUMP				
36	TDO				

	QN68					
Pin Number	A3P030 Function					
37	TRST					
38	VJTAG					
39	IO40RSB0					
40	IO37RSB0					
41	GDB0/IO34RSB0					
42	GDA0/IO33RSB0					
43	GDC0/IO32RSB0					
44	VCCIB0					
45	GND					
46	VCC					
47	IO31RSB0					
48	IO29RSB0					
49	IO28RSB0					
50	IO27RSB0					
51	IO25RSB0					
52	IO24RSB0					
53	IO22RSB0					
54	IO21RSB0					
55	IO19RSB0					
56	IO17RSB0					
57	IO15RSB0					
58	IO14RSB0					
59	VCCIB0					
60	GND					
61	VCC					
62	IO12RSB0					
63	IO10RSB0					
64	IO08RSB0					
65	IO06RSB0					
66	IO04RSB0					
67	IO02RSB0					
68	IO00RSB0					



PQ208			PQ208	PQ208			
Pin Number	A3P250 Function	Pin Number	A3P250 Function	Pin Number	A3P250 Function		
1	GND	37	IO104PDB3	73	IO83RSB2		
2	GAA2/IO118UDB3	38	IO104NDB3	74	IO82RSB2		
3	IO118VDB3	39	IO103PSB3	75	IO81RSB2		
4	GAB2/IO117UDB3	40	VCCIB3	76	IO80RSB2		
5	IO117VDB3	41	GND	77	IO79RSB2		
6	GAC2/IO116UDB3	42	IO101PDB3	78	IO78RSB2		
7	IO116VDB3	43	IO101NDB3	79	IO77RSB2		
8	IO115UDB3	44	GEC1/IO100PDB3	80	IO76RSB2		
9	IO115VDB3	45	GEC0/IO100NDB3	81	GND		
10	IO114UDB3	46	GEB1/IO99PDB3	82	IO75RSB2		
11	IO114VDB3	47	GEB0/IO99NDB3	83	IO74RSB2		
12	IO113PDB3	48	GEA1/IO98PDB3	84	IO73RSB2		
13	IO113NDB3	49	GEA0/IO98NDB3	85	IO72RSB2		
14	IO112PDB3	50	VMV3	86	IO71RSB2		
15	IO112NDB3	51	GNDQ	87	IO70RSB2		
16	VCC	52	GND	88	VCC		
17	GND	53	NC	89	VCCIB2		
18	VCCIB3	54	NC	90	IO69RSB2		
19	IO111PDB3	55	GEA2/IO97RSB2	91	IO68RSB2		
20	IO111NDB3	56	GEB2/IO96RSB2	92	IO67RSB2		
21	GFC1/IO110PDB3	57	GEC2/IO95RSB2	93	IO66RSB2		
22	GFC0/IO110NDB3	58	IO94RSB2	94	IO65RSB2		
23	GFB1/IO109PDB3	59	IO93RSB2	95	IO64RSB2		
24	GFB0/IO109NDB3	60	IO92RSB2	96	GDC2/IO63RSB2		
25	VCOMPLF	61	IO91RSB2	97	GND		
26	GFA0/IO108NPB3	62	VCCIB2	98	GDB2/IO62RSB2		
27	VCCPLF	63	IO90RSB2	99	GDA2/IO61RSB2		
28	GFA1/IO108PPB3	64	IO89RSB2	100	GNDQ		
29	GND	65	GND	101	ТСК		
30	GFA2/IO107PDB3	66	IO88RSB2	102	TDI		
31	IO107NDB3	67	IO87RSB2	103	TMS		
32	GFB2/IO106PDB3	68	IO86RSB2	104	VMV2		
33	IO106NDB3	69	IO85RSB2	105	GND		
34	GFC2/IO105PDB3	70	IO84RSB2	106	VPUMP		
35	IO105NDB3	71	VCC	107	NC		
36	NC	72	VCCIB2	108	TDO		

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PQ208		P	Q208	PQ208		
Pin Number	A3P400 Function	Pin Number	A3P400 Function	Pin Number	A3P400 Function	
109	TRST	145	IO64PDB1	181	IO27RSB0	
110	VJTAG	146	IO63NDB1	182	IO26RSB0	
111	GDA0/IO79VDB1	147	IO63PDB1	183	IO25RSB0	
112	GDA1/IO79UDB1	148	IO62NDB1	184	IO24RSB0	
113	GDB0/IO78VDB1	149	GBC2/IO62PDB1	185	IO23RSB0	
114	GDB1/IO78UDB1	150	IO61NDB1	186	VCCIB0	
115	GDC0/IO77VDB1	151	GBB2/IO61PDB1	187	VCC	
116	GDC1/IO77UDB1	152	IO60NDB1	188	IO21RSB0	
117	IO76VDB1	153	GBA2/IO60PDB1	189	IO20RSB0	
118	IO76UDB1	154	VMV1	190	IO19RSB0	
119	IO75NDB1	155	GNDQ	191	IO18RSB0	
120	IO75PDB1	156	GND	192	IO17RSB0	
121	IO74RSB1	157	VMV0	193	IO16RSB0	
122	GND	158	GBA1/IO59RSB0	194	IO15RSB0	
123	VCCIB1	159	GBA0/IO58RSB0	195	GND	
124	NC	160	GBB1/IO57RSB0	196	IO13RSB0	
125	NC	161	GBB0/IO56RSB0	197	IO11RSB0	
126	VCC	162	GND	198	IO09RSB0	
127	IO72NDB1	163	GBC1/IO55RSB0	199	IO07RSB0	
128	GCC2/IO72PDB1	164	GBC0/IO54RSB0	200	VCCIB0	
129	GCB2/IO71PSB1	165	IO52RSB0	201	GAC1/IO05RSB0	
130	GND	166	IO49RSB0	202	GAC0/IO04RSB0	
131	GCA2/IO70PSB1	167	IO46RSB0	203	GAB1/IO03RSB0	
132	GCA1/IO69PDB1	168	IO43RSB0	204	GAB0/IO02RSB0	
133	GCA0/IO69NDB1	169	IO40RSB0	205	GAA1/IO01RSB0	
134	GCB0/IO68NDB1	170	VCCIB0	206	GAA0/IO00RSB0	
135	GCB1/IO68PDB1	171	VCC	207	GNDQ	
136	GCC0/IO67NDB1	172	IO36RSB0	208	VMV0	
137	GCC1/IO67PDB1	173	IO35RSB0			
138	IO66NDB1	174	IO34RSB0			
139	IO66PDB1	175	IO33RSB0			
140	VCCIB1	176	IO32RSB0			
141	GND	177	IO31RSB0			
142	VCC	178	GND			
143	IO65RSB1	179	IO29RSB0			
144	IO64NDB1	180	IO28RSB0			



PQ208			PQ208	PQ208			
Pin Number	A3P1000 Function	Pin Number	A3P1000 Function	Pin Number	A3P1000 Function		
1	GND	37	IO199PDB3	73	IO162RSB2		
2	GAA2/IO225PDB3	38	IO199NDB3	74	IO160RSB2		
3	IO225NDB3	39	IO197PSB3	75	IO158RSB2		
4	GAB2/IO224PDB3	40	VCCIB3	76	IO156RSB2		
5	IO224NDB3	41	GND	77	IO154RSB2		
6	GAC2/IO223PDB3	42	IO191PDB3	78	IO152RSB2		
7	IO223NDB3	43	IO191NDB3	79	IO150RSB2		
8	IO222PDB3	44	GEC1/IO190PDB3	80	IO148RSB2		
9	IO222NDB3	45	GEC0/IO190NDB3	81	GND		
10	IO220PDB3	46	GEB1/IO189PDB3	82	IO143RSB2		
11	IO220NDB3	47	GEB0/IO189NDB3	83	IO141RSB2		
12	IO218PDB3	48	GEA1/IO188PDB3	84	IO139RSB2		
13	IO218NDB3	49	GEA0/IO188NDB3	85	IO137RSB2		
14	IO216PDB3	50	VMV3	86	IO135RSB2		
15	IO216NDB3	51	GNDQ	87	IO133RSB2		
16	VCC	52	GND	88	VCC		
17	GND	53	VMV2	89	VCCIB2		
18	VCCIB3	54	GEA2/IO187RSB2	90	IO128RSB2		
19	IO212PDB3	55	GEB2/IO186RSB2	91	IO126RSB2		
20	IO212NDB3	56	GEC2/IO185RSB2	92	IO124RSB2		
21	GFC1/IO209PDB3	57	IO184RSB2	93	IO122RSB2		
22	GFC0/IO209NDB3	58	IO183RSB2	94	IO120RSB2		
23	GFB1/IO208PDB3	59	IO182RSB2	95	IO118RSB2		
24	GFB0/IO208NDB3	60	IO181RSB2	96	GDC2/IO116RSB2		
25	VCOMPLF	61	IO180RSB2	97	GND		
26	GFA0/IO207NPB3	62	VCCIB2	98	GDB2/IO115RSB2		
27	VCCPLF	63	IO178RSB2	99	GDA2/IO114RSB2		
28	GFA1/IO207PPB3	64	IO176RSB2	100	GNDQ		
29	GND	65	GND	101	TCK		
30	GFA2/IO206PDB3	66	IO174RSB2	102	TDI		
31	IO206NDB3	67	IO172RSB2	103	TMS		
32	GFB2/IO205PDB3	68	IO170RSB2	104	VMV2		
33	IO205NDB3	69	IO168RSB2	105	GND		
34	GFC2/IO204PDB3	70	IO166RSB2	106	VPUMP		
35	IO204NDB3	71	VCC	107	GNDQ		
36	VCC	72	VCCIB2	108	TDO		



FG256					
Pin Number	A3P1000 Function				
R5	IO168RSB2				
R6	IO163RSB2				
R7	IO157RSB2				
R8	IO149RSB2				
R9	IO143RSB2				
R10	IO138RSB2				
R11	IO131RSB2				
R12	IO125RSB2				
R13	GDB2/IO115RSB2				
R14	TDI				
R15	GNDQ				
R16	TDO				
T1	GND				
T2	IO183RSB2				
Т3	GEB2/IO186RSB2				
T4	IO172RSB2				
T5	IO170RSB2				
T6	IO164RSB2				
T7	IO158RSB2				
Т8	IO153RSB2				
Т9	IO142RSB2				
T10	IO135RSB2				
T11	IO130RSB2				
T12	GDC2/IO116RSB2				
T13	IO120RSB2				
T14	GDA2/IO114RSB2				
T15	TMS				
T16	GND				



FG484			FG484		FG484
Pin Number	A3P600 Function	Pin Number	A3P600 Function	Pin Number	A3P600 Function
R17	GDB1/IO87PPB1	U9	IO131RSB2	W1	NC
R18	GDC1/IO86PDB1	U10	IO124RSB2	W2	IO148PDB3
R19	IO84NDB1	U11	IO119RSB2	W3	NC
R20	VCC	U12	IO107RSB2	W4	GND
R21	IO81NDB1	U13	IO104RSB2	W5	IO137RSB2
R22	IO82PDB1	U14	IO97RSB2	W6	GEB2/IO142RSB2
T1	IO152PDB3	U15	VMV1	W7	IO134RSB2
T2	IO152NDB3	U16	ТСК	W8	IO125RSB2
Т3	NC	U17	VPUMP	W9	IO123RSB2
T4	IO150NDB3	U18	TRST	W10	IO118RSB2
T5	IO147PPB3	U19	GDA0/IO88NDB1	W11	IO115RSB2
Т6	GEC1/IO146PPB3	U20	NC	W12	IO111RSB2
T7	IO140RSB2	U21	IO83NDB1	W13	IO106RSB2
Т8	GNDQ	U22	NC	W14	IO102RSB2
Т9	GEA2/IO143RSB2	V1	NC	W15	GDC2/IO91RSB2
T10	IO126RSB2	V2	NC	W16	IO93RSB2
T11	IO120RSB2	V3	GND	W17	GDA2/IO89RSB2
T12	IO108RSB2	V4	GEA1/IO144PDB3	W18	TMS
T13	IO103RSB2	V5	GEA0/IO144NDB3	W19	GND
T14	IO99RSB2	V6	IO139RSB2	W20	NC
T15	GNDQ	V7	GEC2/IO141RSB2	W21	NC
T16	IO92RSB2	V8	IO132RSB2	W22	NC
T17	VJTAG	V9	IO127RSB2	Y1	VCCIB3
T18	GDC0/IO86NDB1	V10	IO121RSB2	Y2	IO148NDB3
T19	GDA1/IO88PDB1	V11	IO114RSB2	Y3	NC
T20	NC	V12	IO109RSB2	Y4	NC
T21	IO83PDB1	V13	IO105RSB2	Y5	GND
T22	IO82NDB1	V14	IO98RSB2	Y6	NC
U1	IO149PDB3	V15	IO96RSB2	Y7	NC
U2	IO149NDB3	V16	GDB2/IO90RSB2	Y8	VCC
U3	NC	V17	TDI	Y9	VCC
U4	GEB1/IO145PDB3	V18	GNDQ	Y10	NC
U5	GEB0/IO145NDB3	V19	TDO	Y11	NC
U6	VMV2	V20	GND	Y12	NC
U7	IO138RSB2	V21	NC	Y13	NC
U8	IO136RSB2	V22	NC	Y14	VCC

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FG484					
Pin Number	A3P1000 Function				
Y15	VCC				
Y16	NC				
Y17	NC				
Y18	GND				
Y19	NC				
Y20	NC				
Y21	NC				
Y22	VCCIB1				
AA1	GND				
AA2	VCCIB3				
AA3	NC				
AA4	IO181RSB2				
AA5	IO178RSB2				
AA6	IO175RSB2				
AA7	IO169RSB2				
AA8	IO166RSB2				
AA9	IO160RSB2				
AA10	IO152RSB2				
AA11	IO146RSB2				
AA12	IO139RSB2				
AA13	IO133RSB2				
AA14	NC				
AA15	NC				
AA16	IO122RSB2				
AA17	IO119RSB2				
AA18	IO117RSB2				
AA19	NC				
AA20	NC				
AA21	VCCIB1				
AA22	GND				
AB1	GND				
AB2	GND				
AB3	VCCIB2				
AB4	IO180RSB2				
AB5	IO176RSB2				
AB6	IO173RSB2				

FG484		
Pin Number	A3P1000 Function	
AB7	IO167RSB2	
AB8	IO162RSB2	
AB9	IO156RSB2	
AB10	IO150RSB2	
AB11	IO145RSB2	
AB12	IO144RSB2	
AB13	IO132RSB2	
AB14	IO127RSB2	
AB15	IO126RSB2	
AB16	IO123RSB2	
AB17	IO121RSB2	
AB18	IO118RSB2	
AB19	NC	
AB20	VCCIB2	
AB21	GND	
AB22	GND	



Revision	Changes	Page
v2.0 (continued)	Table 3-20 • Summary of I/O Timing Characteristics—Software Default Settings (Advanced) and Table 3-21 • Summary of I/O Timing Characteristics—Software Default Settings (Standard Plus) were updated.	3-20 to 3-20
	Table 3-11 • Different Components Contributing to Dynamic Power Consumptionin ProASIC3 Devices was updated.	3-9
	Table 3-24 • I/O Output Buffer Maximum Resistances1 (Advanced) and Table 3-25 • I/O Output Buffer Maximum Resistances1 (Standard Plus) were updated.	3-22 to 3-22
	Table 3-17 • Summary of Maximum and Minimum DC Input Levels Applicable to Commercial and Industrial Conditions was updated.	3-18
	Table 3-28 • I/O Short Currents IOSH/IOSL (Advanced) and Table 3-29 • I/O Short Currents IOSH/IOSL (Standard Plus) were updated.	3-24 to 3-26
	The note in Table 3-32 • I/O Input Rise Time, Fall Time, and Related I/O Reliability was updated.	3-27
	Figure 3-33 • Write Access After Write onto Same Address, Figure 3-34 • Read Access After Write onto Same Address, and Figure 3-35 • Write Access After Read onto Same Address are new.	3-82 to 3-84
	Figure 3-43 • Timing Diagram was updated.	3-96
	Ambient was deleted from the "Speed Grade and Temperature Grade Matrix".	iv
	Notes were added to the package diagrams identifying if they were top or bottom view.	N/A
	The A3P030 "132-Pin QFN" table is new.	4-2
	The A3P060 "132-Pin QFN" table is new.	4-4
	The A3P125 "132-Pin QFN" table is new.	4-6
	The A3P250 "132-Pin QFN" table is new.	4-8
	The A3P030 "100-Pin VQFP" table is new.	4-11
Advance v0.7 (January 2007)	In the "I/Os Per Package" table, the I/O numbers were added for A3P060, A3P125, and A3P250. The A3P030-VQ100 I/O was changed from 79 to 77.	ii
Advance v0.6 (April 2006)	The term flow-through was changed to pass-through.	N/A
	Table 1 was updated to include the QN132.	ii
	The "I/Os Per Package" table was updated with the QN132. The footnotes were also updated. The A3P400-FG144 I/O count was updated.	ii
	"Automotive ProASIC3 Ordering Information" was updated with the QN132.	iii
	"Temperature Grade Offerings" was updated with the QN132.	iii
	B-LVDS and M-LDVS are new I/O standards added to the datasheet.	N/A
	The term flow-through was changed to pass-through.	N/A
	Figure 2-7 • Efficient Long-Line Resources was updated.	2-7
	The footnotes in Figure 2-15 • Clock Input Sources Including CLKBUF, CLKBUF_LVDS/LVPECL, and CLKINT were updated.	2-16
	The Delay Increments in the Programmable Delay Blocks specification in Figure 2-24 • ProASIC3E CCC Options.	2-24
	The "SRAM and FIFO" section was updated.	2-21



Datasheet Information

Revision	Changes	Page
Advance v0.3	The "PLL Macro" section was updated. EXTFB information was removed from this section.	2-15
	The CCC Output Peak-to-Peak Period Jitter F <sub>CCC_OUT</sub> was updated in Table 2- 11 • ProASIC3 CCC/PLL Specification	2-29
	EXTFB was removed from Figure 2-27 • CCC/PLL Macro.	2-28
	Table 2-13 • ProASIC3 I/O Features was updated.	2-30
	The "Hot-Swap Support" section was updated.	2-33
	The "Cold-Sparing Support" section was updated.	2-34
	"Electrostatic Discharge (ESD) Protection" section was updated.	2-35
	The LVPECL specification in Table 2-43 • I/O Hot-Swap and 5 V Input Tolerance Capabilities in ProASIC3 Devices was updated.	2-64
	In the Bank 1 area of Figure 2-72, VMV2 was changed to VMV1 and VCCIB2 was changed to VCC <sub>1</sub> B1.	2-97
	The VJTAG and I/O pin descriptions were updated in the "Pin Descriptions" section.	2-50
	The "JTAG Pins" section was updated.	2-51
	"128-Bit AES Decryption" section was updated to include M7 device information.	2-53
	Table 3-6 was updated.	3-6
	Table 3-7 was updated.	3-6
	In Table 3-11, PAC4 was updated.	3-93-8
	Table 3-20 was updated.	3-20
	The note in Table 3-32 was updated.	3-27
	All Timing Characteristics tables were updated from LVTTL to Register Delays	3-31 to 3- 73
	The Timing Characteristics for RAM4K9, RAM512X18, and FIFO were updated.	3-85 to 3-90
	F <sub>TCKMAX</sub> was updated in Table 3-110.	3-97
Advance v0.2	Figure 2-11 was updated.	2-9
	The "Clock Resources (VersaNets)" section was updated.	2-9
	The "VersaNet Global Networks and Spine Access" section was updated.	2-9
	The "PLL Macro" section was updated.	2-15
	Figure 2-27 was updated.	2-28
	Figure 2-20 was updated.	2-19
	Table 2-5 was updated.	2-25
	Table 2-6 was updated.	2-25
	The "FIFO Flag Usage Considerations" section was updated.	2-27
	Table 2-13 was updated.	2-30
	Figure 2-24 was updated.	2-31
	The "Cold-Sparing Support" section is new.	2-34